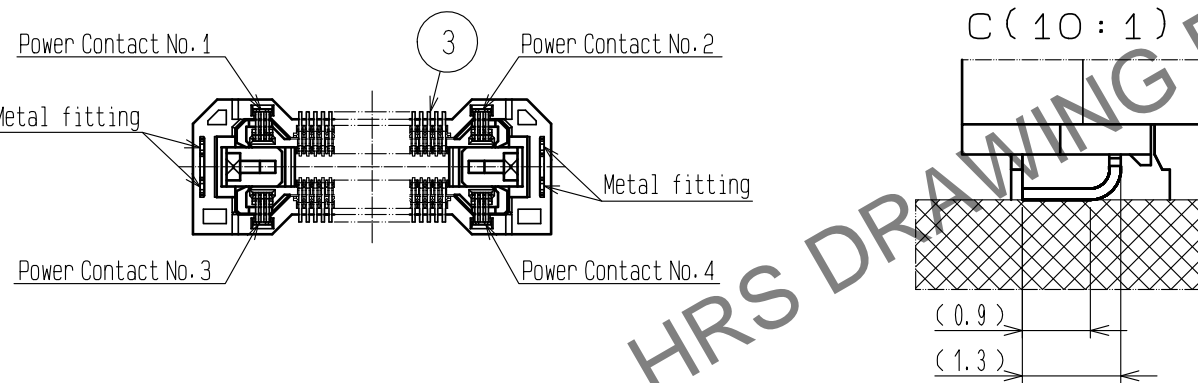
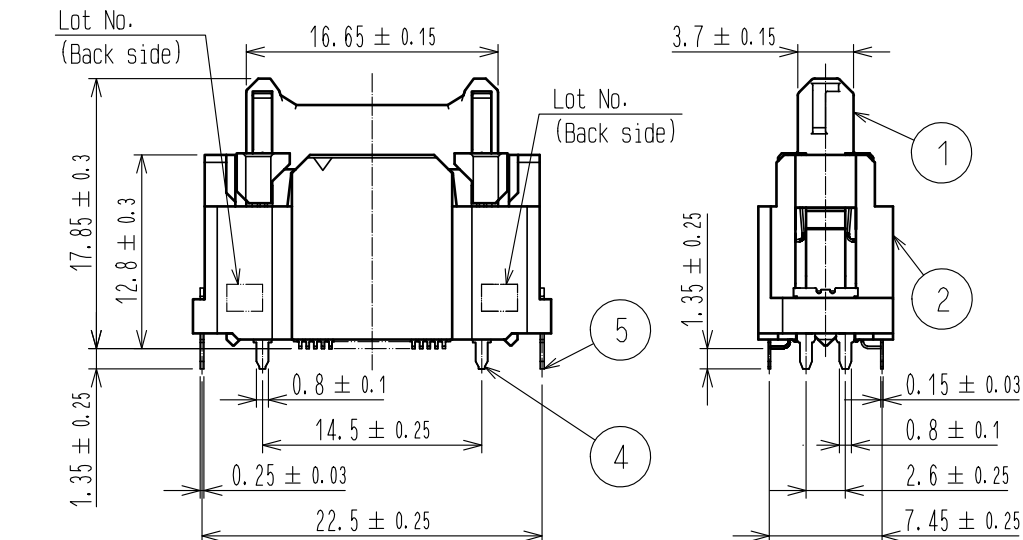
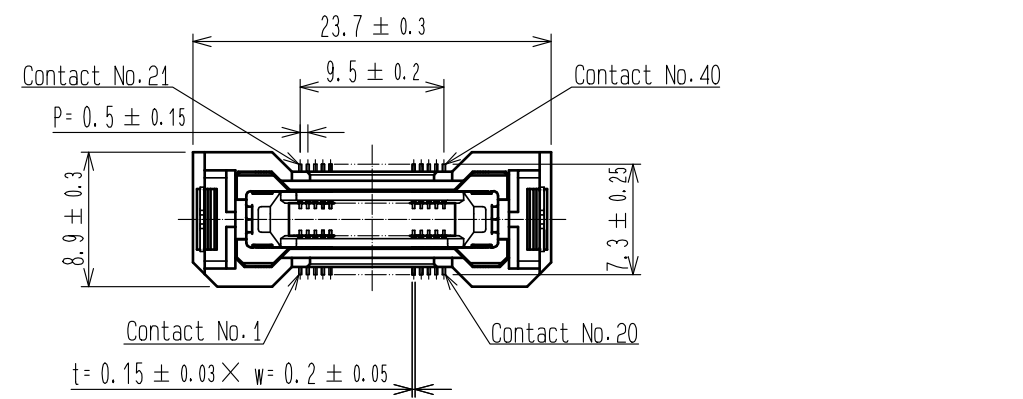
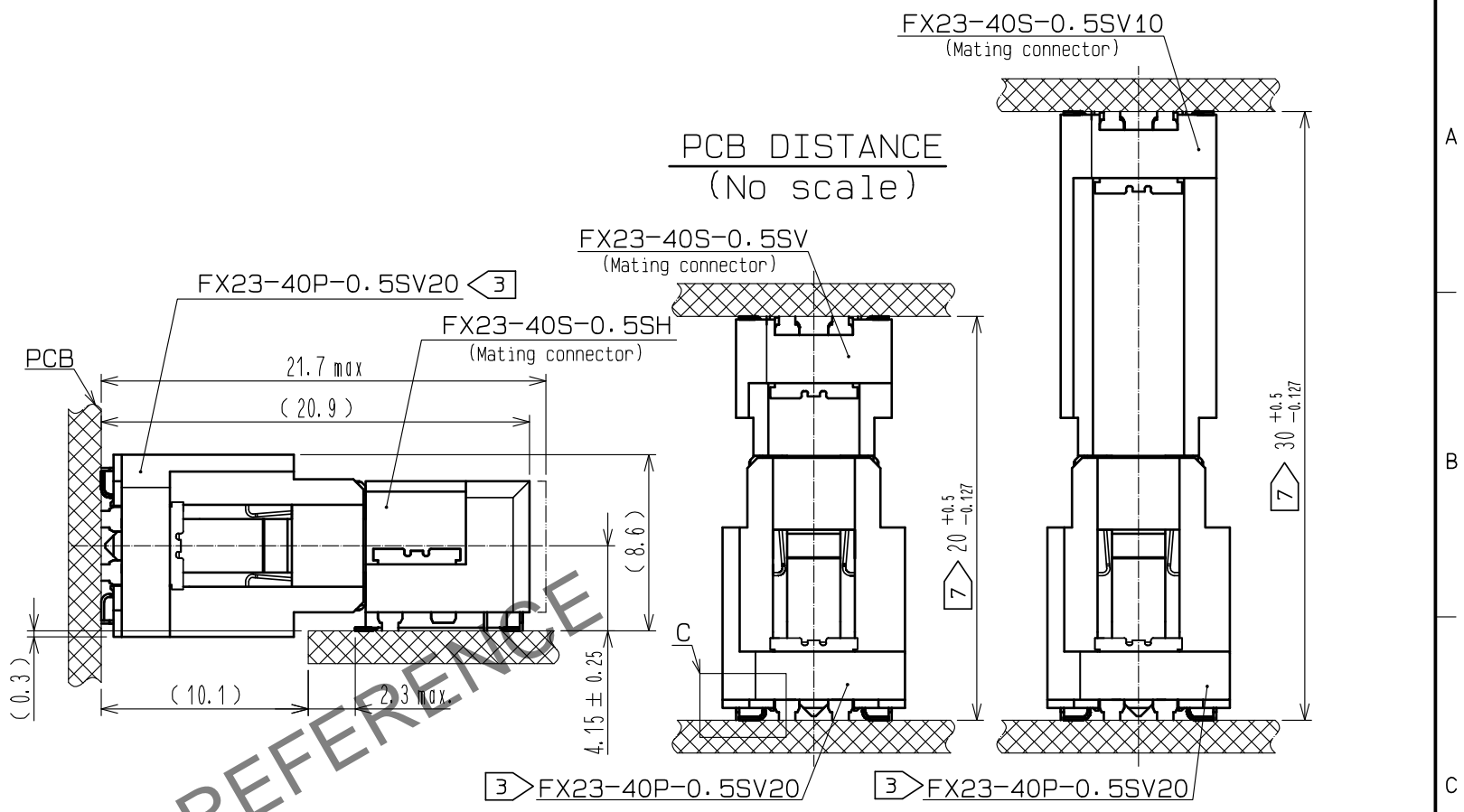
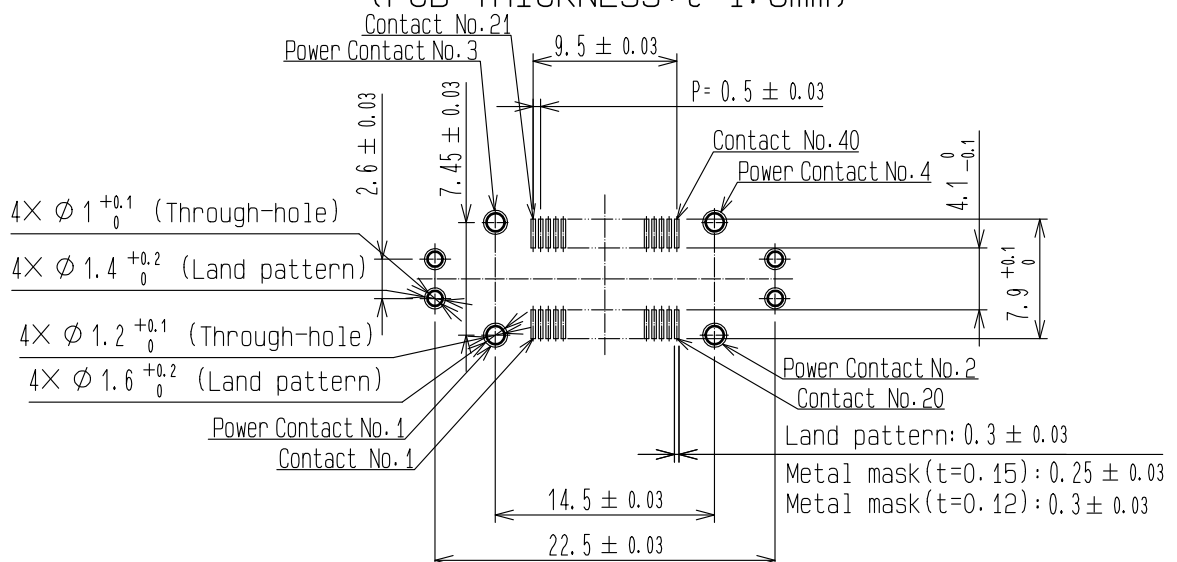


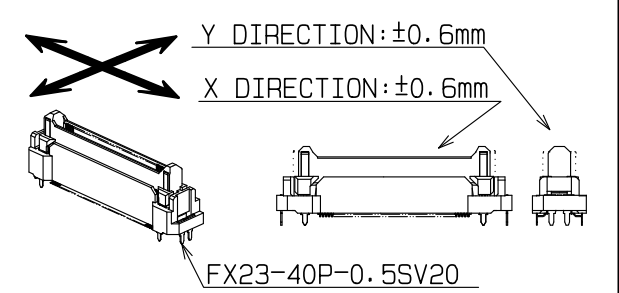
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RECOMMENDED LAND PATTERN DIMENSION OF PCB
 (PCB THICKNESS: t=1.6mm)



FLOATING RANGE



- Note
- 1 Lead CO-Planarity is 0.1mm MAX.
 - 2 This is packaged in embossed carrier tape. (150pcs/RL)
 - 3 Floating range of this connector is ±0.6mm MAX.
 The maximum cycle time of the floating operation is in accordance with the mating cycle of the connector.
 - 4 It shows the vacuum pickup area. Remove the mylar tape before mating connectors.
 - 5 Blemish and hit mark can be occurred through out the manufacturing process which doesn't affect quality level.
 - 6 The dimensions in parentheses are for references.
 - 7 Please use the connectors within the specified PCB distance.
 - 8 Embossed carrier tape, cover tape and plastic reel are composed of antistatic material.

8	POLYIMIDE	(TAPE FOR VACUUM PICKUP)
7	POLYESTER	(EMBOSSSED COVER TAPE)
6	POLYSTYRENE	(EMBOSSSED CARRIER TAPE)
5	BRASS	LEAD AREA: TIN-PLATING 3 μm UNDER PLATING: NICKEL 1 μm
4	COPPER ALLOY	CONTACT AREA: GOLD 0.1 μm LEAD AREA: TIN-PLATING 1 μm UNDER PLATING: NICKEL 1.3 μm
3	COPPER ALLOY	CONTACT AREA: GOLD 0.1 μm LEAD AREA: GOLD 0.03 μm UNDER PLATING: NICKEL 1.3 μm
2	POLYAMIDE	BLACK UL94V-0
1	POLYAMIDE	BLACK UL94V-0

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
8	POLYIMIDE		(TAPE FOR VACUUM PICKUP)	7	POLYESTER		(EMBOSSSED COVER TAPE)
7	POLYESTER		(EMBOSSSED COVER TAPE)	6	POLYSTYRENE		(EMBOSSSED CARRIER TAPE)
6	POLYSTYRENE		(EMBOSSSED CARRIER TAPE)	5	BRASS		LEAD AREA: TIN-PLATING 3 μm UNDER PLATING: NICKEL 1 μm
5	BRASS		LEAD AREA: TIN-PLATING 3 μm UNDER PLATING: NICKEL 1 μm	4	COPPER ALLOY		CONTACT AREA: GOLD 0.1 μm LEAD AREA: TIN-PLATING 1 μm UNDER PLATING: NICKEL 1.3 μm
4	COPPER ALLOY		CONTACT AREA: GOLD 0.1 μm LEAD AREA: TIN-PLATING 1 μm UNDER PLATING: NICKEL 1.3 μm	3	COPPER ALLOY		CONTACT AREA: GOLD 0.1 μm LEAD AREA: GOLD 0.03 μm UNDER PLATING: NICKEL 1.3 μm
3	COPPER ALLOY		CONTACT AREA: GOLD 0.1 μm LEAD AREA: GOLD 0.03 μm UNDER PLATING: NICKEL 1.3 μm	2	POLYAMIDE		BLACK UL94V-0
2	POLYAMIDE		BLACK UL94V-0	1	POLYAMIDE		BLACK UL94V-0

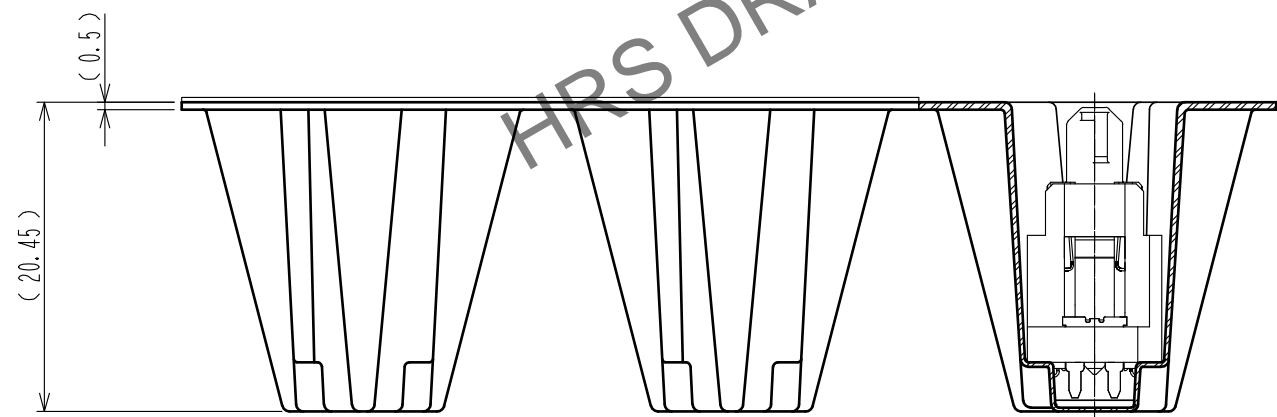
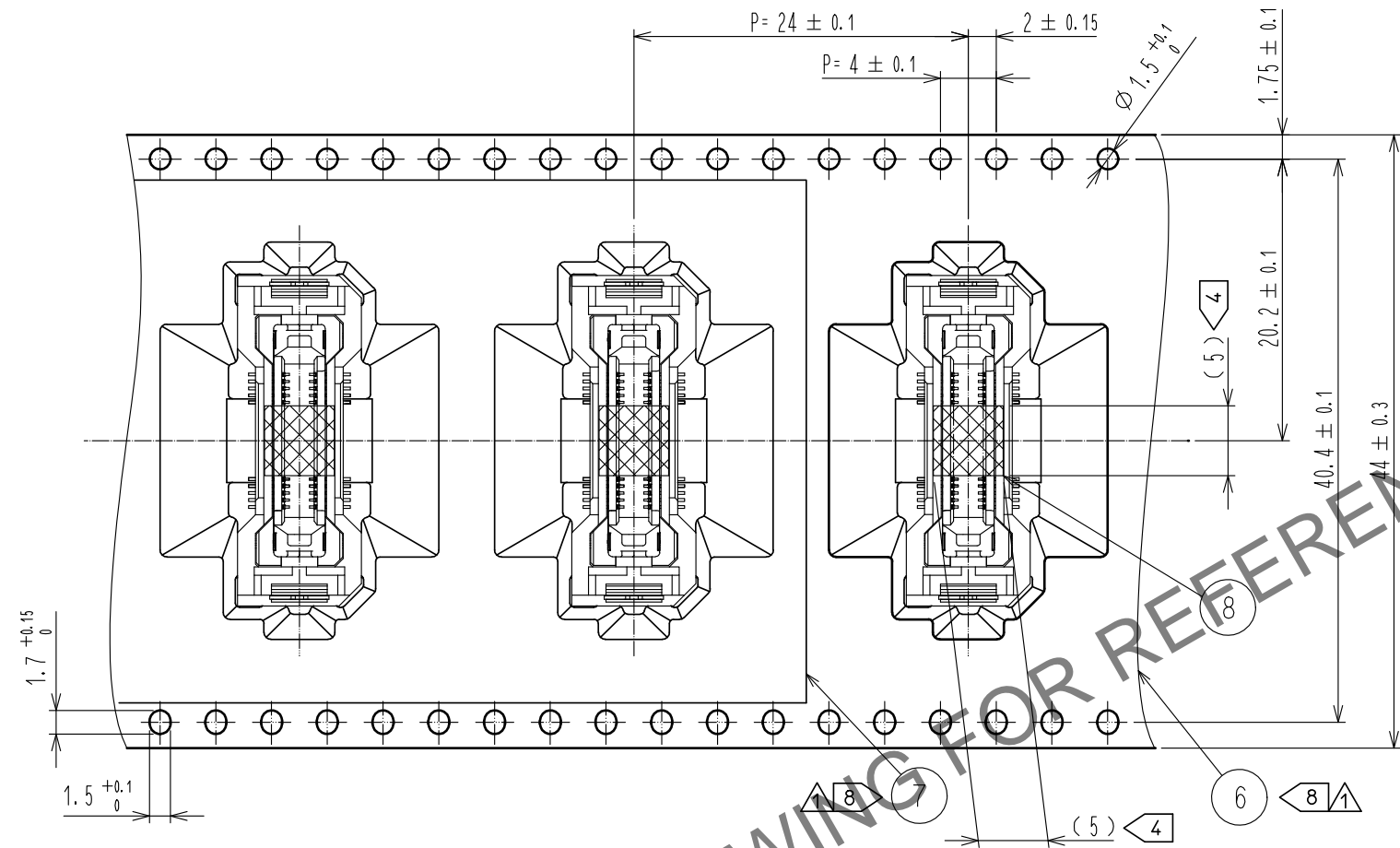
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	5	DIS-F-00005487	TS.00NO	HT. YAMAGUCHI	20191120

APPROVED	: NH. NAKATA	20160928	DRAWING NO.	EDC-353545-20-00
CHECKED	: HT. YAMAGUCHI	20160927	PART NO.	FX23-40P-0.5SV20<20>
DESIGNED	: YJ. ASAO	20160927	CODE NO.	CL573-3102-8-20
DRAWN	: YJ. ASAO	20160927		

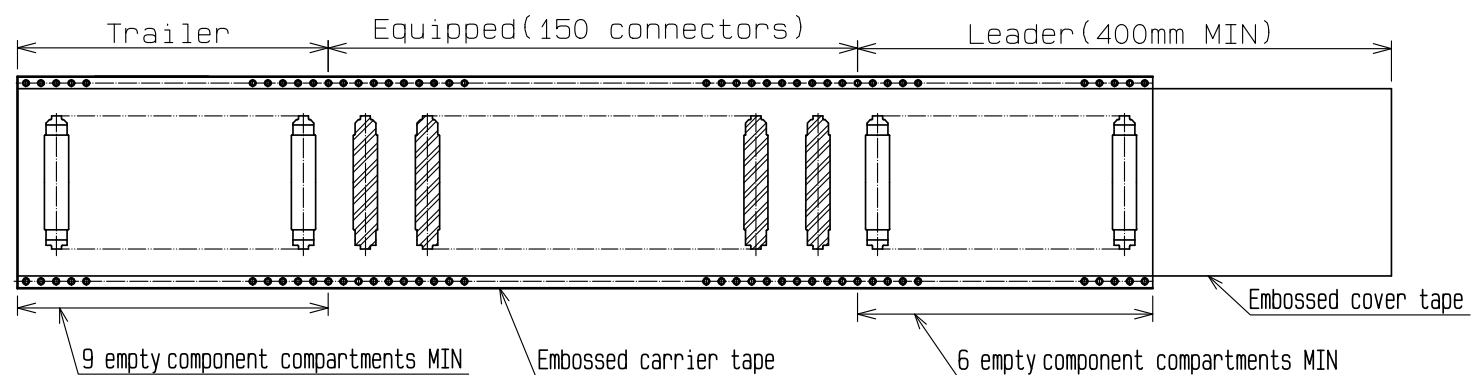
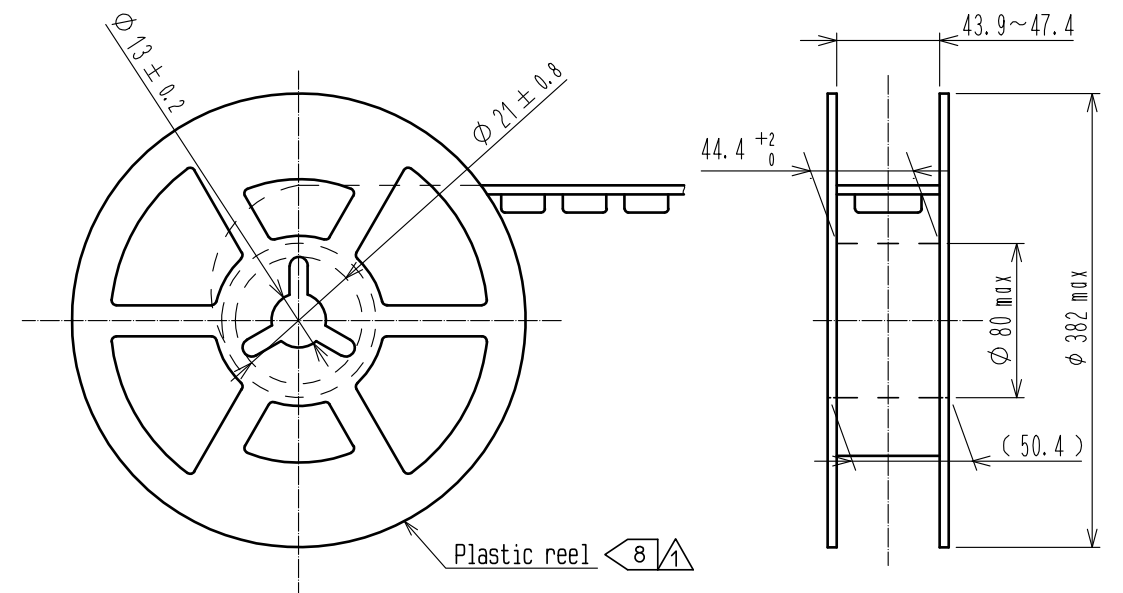
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2 DRAWING FOR PACKING(2:1)

Direction of pulling out →



REEL DIMENSION(No scale)



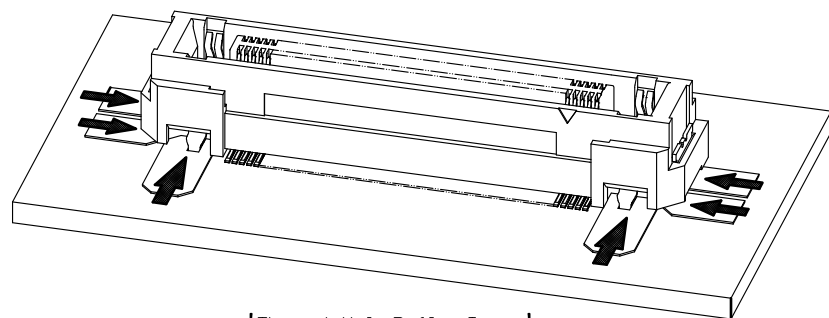
HRS	DRAWING NO.	EDC-353545-20-00
	PART NO.	FX23-40P-0.5SV20(20)
	CODE NO.	CL573-3102-8-20
		$\triangle 1$ 2/3

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In order to prevent any potential failures with the connector, please read the following below:

[Through Hole Reflow Process]

FX23 and FX23L Series use through hole reflow process, where power contacts/metal fittings draw solder paste from the surrounding area. In regards to the soldering paste print area, the surface shall be flat with no exposed copper surface. If the surface is not flat, power contacts/metal fittings may not properly draw the soldering paste, resulting insufficient solder on the power contacts/metal fittings as well as ball-shaped solder on the PCB.



[Through Hole Reflow Image]

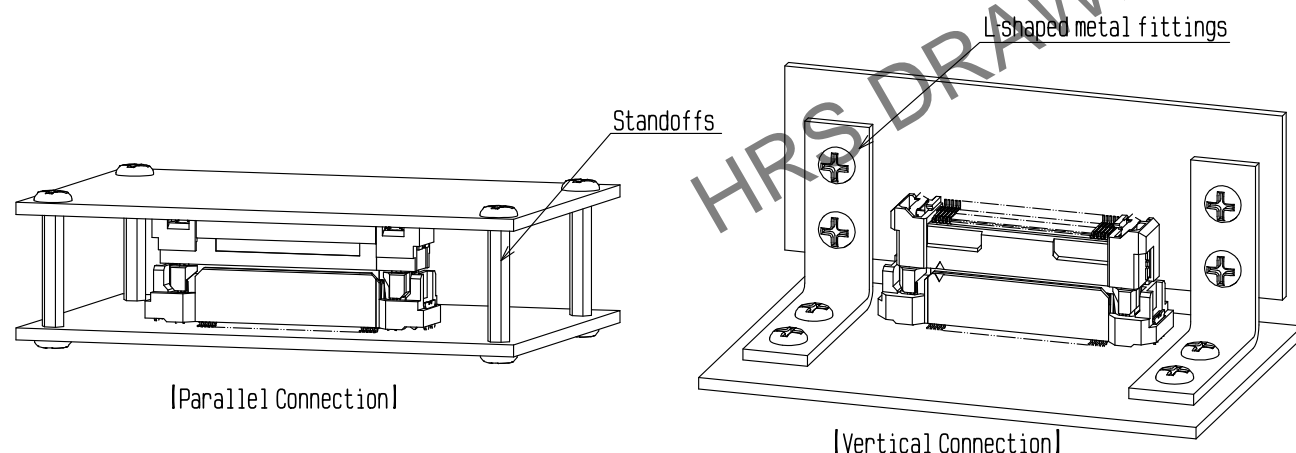
When applying solder from the opposite side of the PCB, due to the unavailability in solder space on the mounting side, there may be a case where solder is insufficiently applied to power contacts/metal fittings. Please check if the power contacts/metal fittings are properly soldered when doing so.

[In Regards to Design Guideline]

To provide more information in regards to the usage of this product, we have prepared a detailed manual (ETAD-F0887-00). Please contact our sales representative if needed.


[Board Stabilization]

This connector can absorb misalignment of boards but cannot absorb vibration itself. When boards are supported by a connector only, the connector will be loaded excessively, which may result in a damage or contact failure. Take measures to secure boards with an object other than connector as shown in the following figure.



Note that when a spacer is installed far from connectors, incomplete mating of the connectors may occur due to sagging of the board, etc. Mate connectors surely and then fix a spacer.

HRS DRAWING FOR REFERENCE

HRS	DRAWING NO.	EDC-353545-20-00	 3/3
	PART NO.	FX23-40P-0.5SV20(20)	
	CODE NO.	CL573-3102-8-20	